



# SOT110-1

plastic single in-line medium power package with fin; 9 leads  
8 February 2016 Package information

## 1. Package summary

<b>Terminal position code</b>	S (single)
<b>Package type descriptive code</b>	SIL9MPF
<b>Package type industry code</b>	SIL9MPF
<b>Package style descriptive code</b>	BCC (bottom chip carrier)
<b>Package style suffix code</b>	MPF (medium power; with fin)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	12-3-2003

Table 1. Package summary

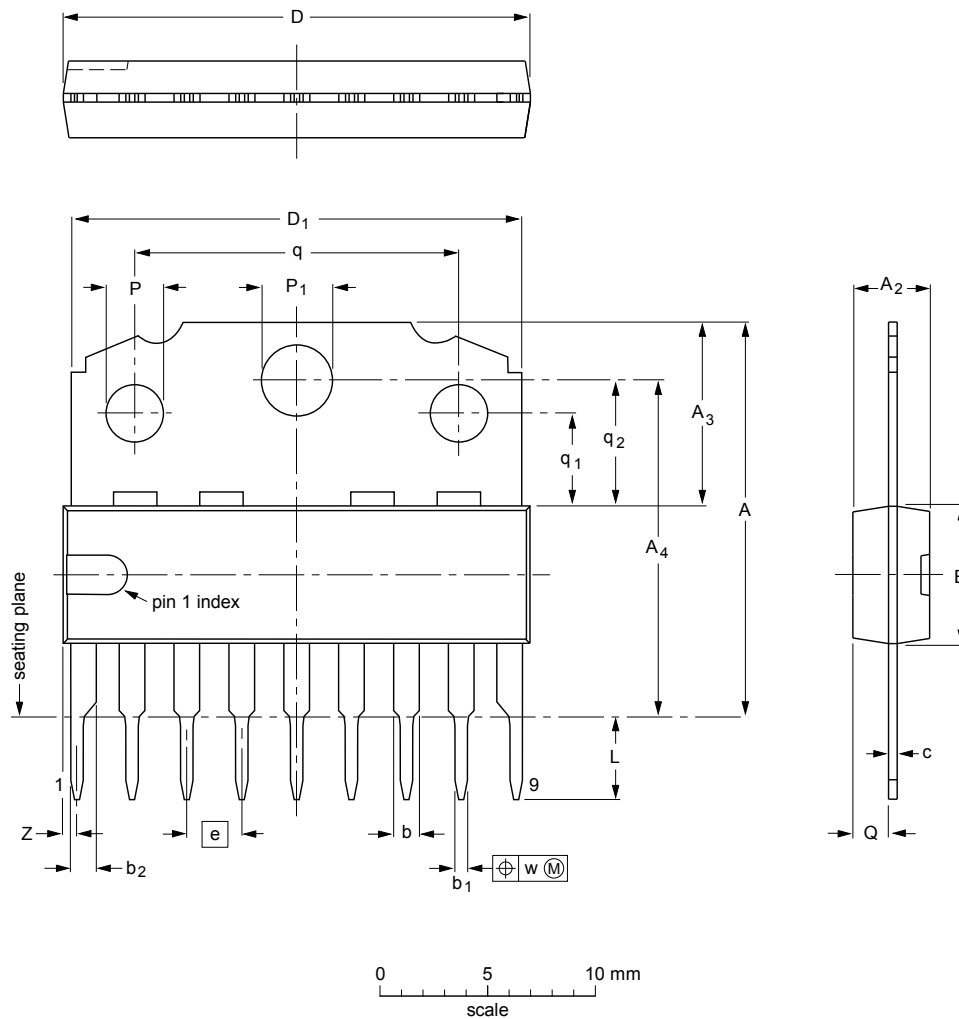
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	21.4	-	21.6	21.8	mm
E	package width	6.2	-	6.35	6.48	mm
A <sub>2</sub>	package height	[tbd]	-	3.55	3.7	mm
n <sub>2</sub>	actual quantity of termination	-	-	9	-	



2. Package outline

SIL9MPF: plastic single in-line medium power package with fin; 9 leads

SOT110-1



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>2</sub> max.	A <sub>3</sub>	A <sub>4</sub>	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	D <sub>1</sub>	E <sup>(1)</sup>	e	L	P	P <sub>1</sub>	Q	q	q <sub>1</sub>	q <sub>2</sub>	w	Z <sup>(1)</sup> max.
mm	18.5 17.8	3.7	8.7 8.0	15.8 15.4	1.40 1.14	0.67 0.50	1.40 1.14	0.48 0.38	21.8 21.4	21.4 20.7	6.48 6.20	2.54	3.9 3.4	2.75 2.50	3.4 3.2	1.75 1.55	15.1 14.9	4.4 4.2	5.9 5.7	0.25	1

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT110-1						95-02-25 03-03-12

Fig. 1. Package outline SIL9MPF (SOT110-1)

### 3. Legal information

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